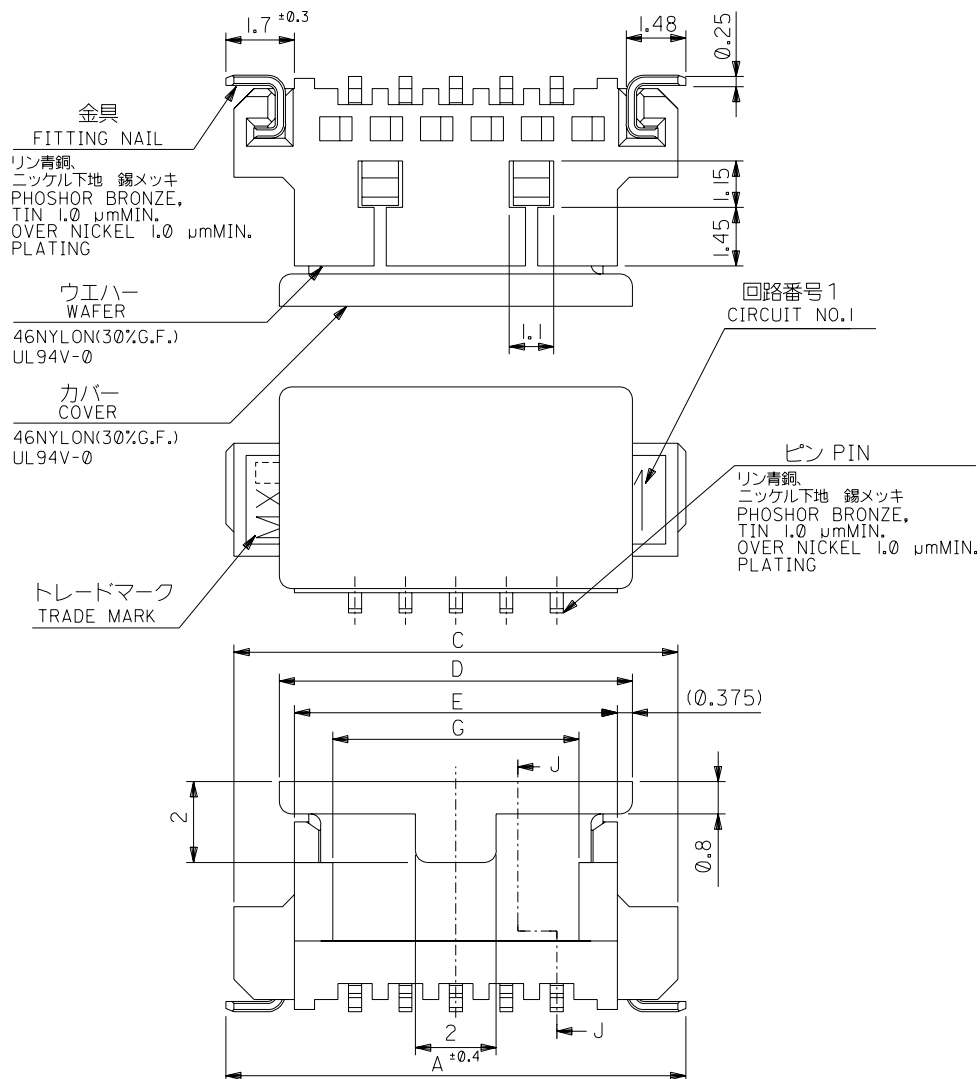
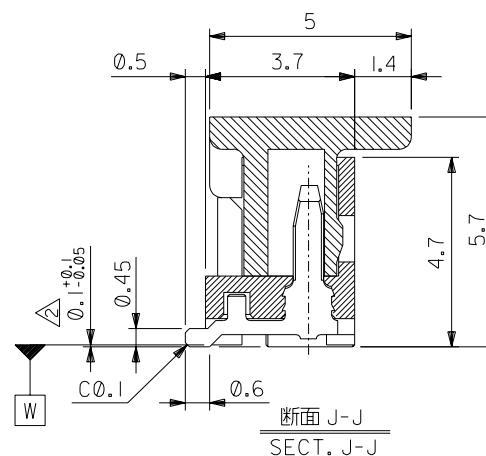




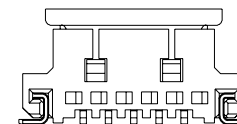
NOTES

1. 嵌合相手:51021シリーズ MATE WITH :51021 SERIES
- △ 水平面上において、ウエハー底面 [W] とソルダーテール及び
フィッティングネイル底面とのズレ量を示す。
MISALIGNMENT OF SOLDER TAIL & FITTING NAIL FROM
- △ 偶数極にのみ適用。APPLY EVEN CIRCUIT PRODUCTS.
4. 本製品は53398-***20の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53398-***20.



17.35	18.05	19.25	20	22.25	16.25	22.3	53398-1429	14
14.85	15.55	16.75	17.5	19.75	13.75	20.15	53398-1229	12
9.85	10.55	11.75	12.5	14.75	8.75	15.15	53398-0829	8
8.6	9.3	10.5	11.25	13.5	7.5	13.9	53398-0729	7
7.35	8.05	9.25	10	12.25	6.25	12.65	53398-0629	6
6.1	6.8	8	8.75	11	5	11.4	53398-0529	5
4.85	5.55	6.75	7.5	9.75	3.75	10.15	53398-0429	4
3.6	4.3	5.5	6.25	8.5	2.5	8.9	53398-0329	3
2.35	3.05	4.25	5	7.25	1.25	7.65	53398-0229	2
G	F	E	D	C	B	A	MATERIAL NO.	CIRCUITS

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	RELEASED '04/02/12 EC NO. J2004-2404 DRWN: Y.SAKIYAMA CHK: M.SASAO APPR: M.SASAO	DESCRIPTION	MATERIAL 材料 SEE DRAWING	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE —	DESIGN UNITS ☒ mm ☐ INCH	THIRD ANGLE PROJECTION	☐ mm ☐ INCH ☒ mm ONLY	REVISE ON CAD ONLY
						FINISH 仕上	10 UNDER 未満	±0.2	DRAWN BY & DATE Y.SAKIYAMA '04/02/12	TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT (ST.) WITH COVER -LEAD FREE-		
							10 OVER 以上	±0.25	CHECKED BY & DATE M.SASAO '04/02/12			
							30 OVER 以上	±0.3	APPROVED BY & DATE M.SASAO '04/02/12	MOLEX INCORPORATED		
						WIRE RANGE 適用電線範囲		ANGLE 角度	CAD FILENAME SD-53398-034.S01	MATERIAL NO. SEE CHART	DRAWING NO. SD-53398-034	SHEET NO. 1 OF 2
					REV	INS. RANGE 被覆外径		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.				SIZE B



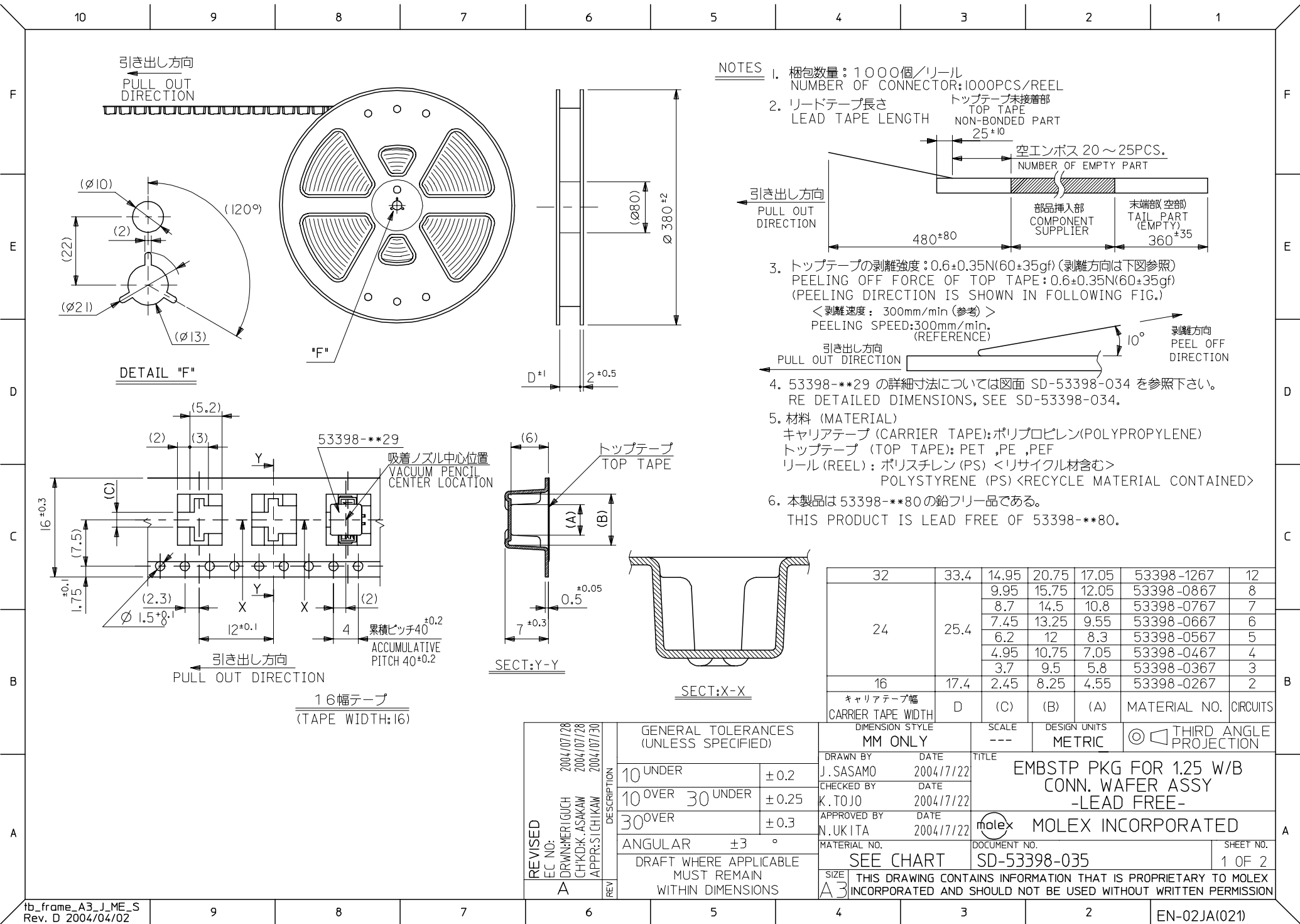
4極以上
OVER 4 CKT.

△5 ロック形状図
LOCK CONFIGURATION

NOTES

△ ロック窓は、2、3極は1ヶ所、4極以上は2ヶ所とする。
LOCKING WINDOW : ONE PLACE FOR 2&3 CKTS.
TWO PLACES FOR MORE THAN 4 CKTS.

EC NO. DRWN: CH'K: APPR:	EC NO. DRWN: CH'K: APPR:	EC NO. DRWN: CH'K: APPR:	EC NO. DRWN: CH'K: APPR:	RELEASED '04/02/12 EC NO. J2004-2404 DRWN: Y.SAKIYAMA CH'K: M.SASAO APPR: M.SASAO	DESCRIPTION	MATERIAL 材料	SEE NOTES	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE ——	MODEL NO. DESIGN UNITS ☒ mm ☐ INCH	53398-**-29	DIMENSIONS: ☐ mm ☐ INCH ☒ mm ONLY	SHT REVISE ON CAD ONLY	REV
						FINISH 仕上げ		10 UNDER 未満	±0.2	DRAWN BY & DATE Y.SAKIYAMA '04/02/12	TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT (ST.) WITH COVER -LEAD FREE-			
						WIRE RANGE 適用電線範囲		10 OVER 以上	30 UNDER 未満	±0.25		CHECKED BY & DATE M.SASAO '04/02/12		
								30 OVER 以上	±0.3	APPROVED BY & DATE M.SASAO '04/02/12		 MOLEX INCORPORATED		
						ANGLE 角度		±3°	CAD FILENAME SD-53398-034.S02	MATERIAL NO. SEE CHART	DRAWING NO. SD-53398-034	SHEET NO. 2 OF 2		
INS. RANGE 被覆外径	——		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.											SIZE B



10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

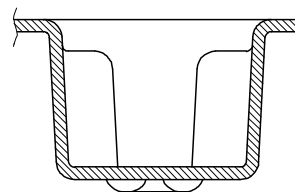
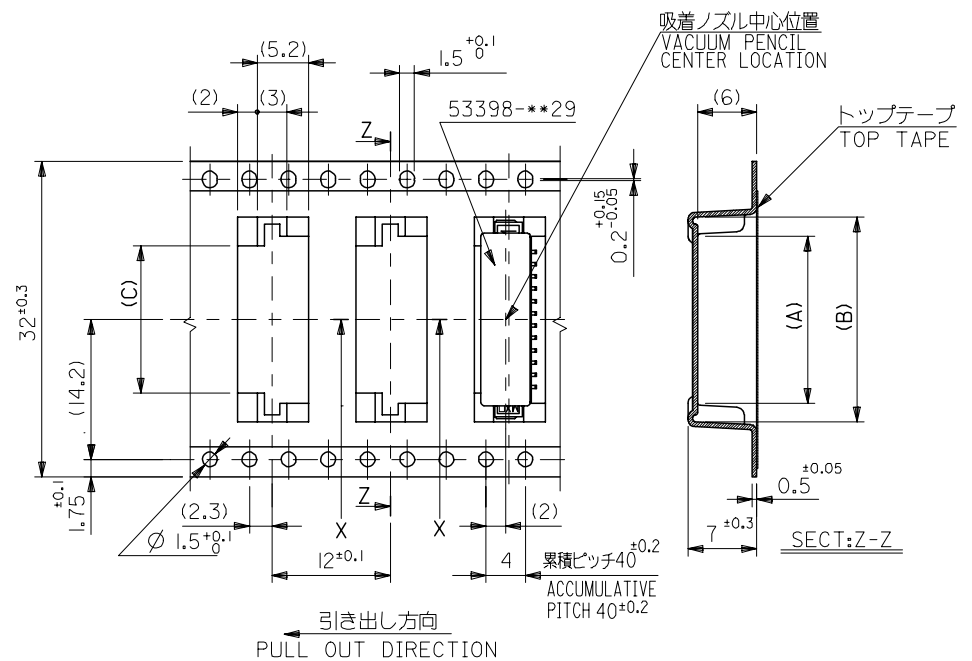
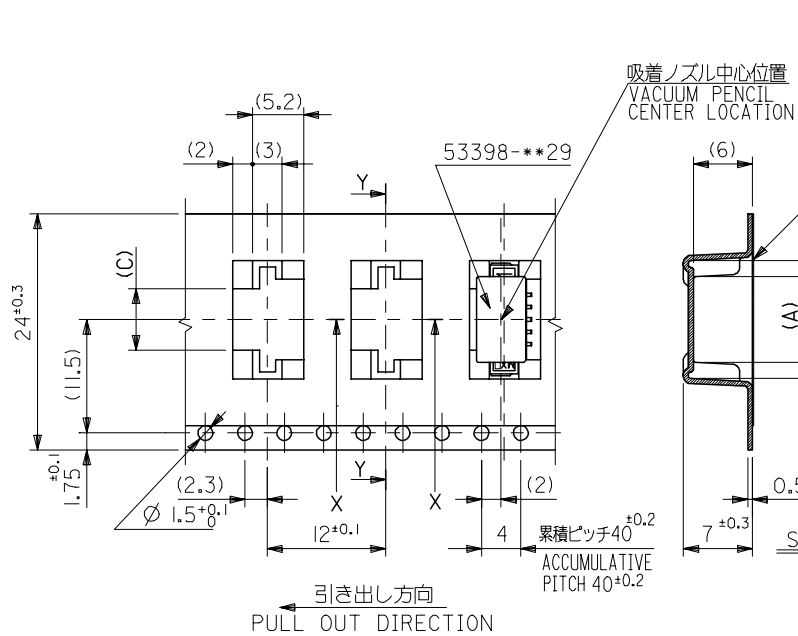
E

D

C

B

A



SECT:X-X

REVISED EC NO: 2004/07/28 DRAWN: M. ICHIKAWA CHKD: K. ASAKAWA APPR: S. ICHIKAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY J. SASAMO	DATE 2004/7/22	TITLE EMBSTP PKG FOR 1.25 W/B CONN. WAFER ASSY -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/7/22					
		30 OVER	±0.3	APPROVED BY N. UKITA	DATE 2004/7/22	MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-53398-035		2 OF 2		
A	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								